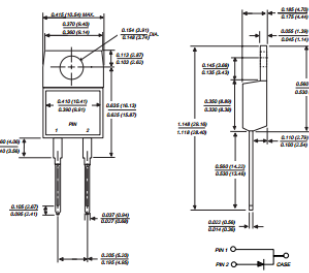


FES8AT THRU FES8JT

FAST EFFICIENT PLASTIC RECTIFIER
 Reverse Voltage - 50 to 600 Volts Forward Current - 8.0 Amperes

TO-220AC



Dimensions in inches and (millimeters)

FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junction
- Low leakage, high voltage
- High surge current capability
- Superfast recovery time, for high efficiency
- High temperature soldering guaranteed: 250°C, 0.16" (4.06mm) from case for 10 seconds



MECHANICAL DATA

Case: JEDEC TO-220AC fully overmolded plastic body over passivated chip
Terminals: Plated lead solderable per MIL-STD-750, Method 2026
Polarity: As marked
Mounting Position: Any
Mounting Torque: 5 in. - lbs. max.
Weight: 0.064 ounce, 1.81 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

	SYMBOLS	FES 8AT	FES 8BT	FES 8CT	FES 8DT	FES 8FT	FES 8GT	FES 8HT	FES 8JT	UNITS
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	150	200	300	400	500	600	Volts
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	350	420	Volts
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	500	600	Volts
Maximum average forward rectified current at T _C =100°C	I _(AV)	8.0								Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	125.0								Amps
Maximum instantaneous forward voltage at 8.0A	V _F	0.95		1.3		1.5				Volts
Maximum DC reverse current at T _C =25°C at rated DC blocking voltage at T _C =100°C	I _R	10.0 500.0								µA
Maximum reverse recovery time (NOTE 1)	t _{rr}	35.0		50.0						ns
Typical junction capacitance (NOTE 2)	C _J	85.0				60.0				pF

Typical thermal resistance (NOTE 3)	R _{θJA}	15.0	°C/W
(NOTE 4)	R _{θJC} <td>2.2</td> <td></td>	2.2	
Operating junction and storage temperature range	T _J , T _{STG}	-65 to +150	°C

NOTES:

- (1) Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_{SM}=0.25A
- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
- (3) Thermal resistance from junction to ambient in free air, no heatsink
- (4) Thermal resistance from junction to case mounted on heatsink

FIG. 1 - MAXIMUM FORWARD CURRENT DERATING CURVES

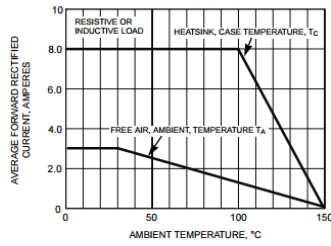


FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

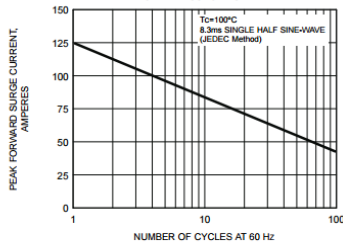


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

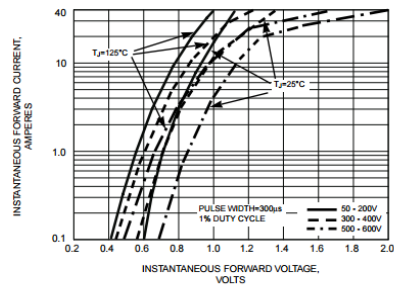


FIG. 4 - TYPICAL REVERSE LEAKAGE CHARACTERISTICS

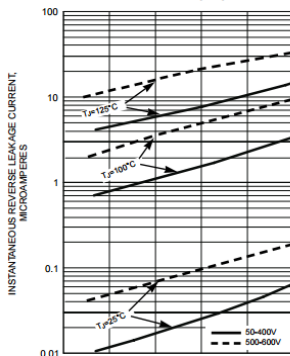


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

